Document Number: 1 Rev. 1, 02/2023

# **Real-Time Drivers Product Brief-S32G**

### Contents

1.	Software Product Overview	1
2.	Software Content	2
3.	Supported Targets	4
4.	Quality, Standards Compliance and Testing Approach	4
5	Document Information	-

### 1. Software Product Overview

S32-based platform products offer Real-Time Drivers (RTD) software supporting both AUTOSAR and non-AUTOSAR (similar to traditional SDKs) applications. Both are ISO 26262 functional safety compliant up to ASIL D. A wide range of standard low-level drivers (LLD) and complex device drivers (CDD) create a rich ecosystem integrated into a unified development environment with highly optimized code. Each driver provides two sets of APIs: one compliant with AUTOSAR and the other directly accessing the hardware. For a non-AUTOSAR application, any interface can be used, according to the scope of the application.

RTD software is developed using Automotive SPICE/CMMI Level 3, MISRA 2012, and ISO 26262 compliant processes – all automotivegrade quality and production ready. RTD software includes S32CT (non-AUTOSAR) configurators and supports Elektrobit tresos (AUTOSAR) and multiple premium IDE toolchains.

#### Software Content



Figure 1. NXP's Real-Time Drivers (RTD) Software Environment

### 2. Software Content

The list of high-level drivers (AUTOSAR compliant + extensions) include:

• Adc	• McI	• Det
• Base	• Mcu	• Ecuc
• Can	• Ocotp	• Os
• Crc	• Ocu	• Ecum
Crypto	Platform	• Wdglf
• Dio	• Port	• MemIf
• <i>Eep</i>	• Pwm	• Ethlf
• Eth	• Qd	EthTrcv
• Fee	• <i>Rm</i>	• EthSwt
• Fls	• Spi	• Linlf
• Fr	• Thermal	• Canlf
• Gpt	• Uart	• Crylf
• 12c	• Wdg	• Csm
• lcu	Resource	• Rte
• Lin	• Dem	• Frlf

#### Software Content

<b>RTD Driver</b>	RTD LowLevel Interface	IP
	Ctu_lp	СТИ
ADC	Adc_Sar_Ip	SAR_ADC
BASE	NA	REG_PROT
CAN	FlexCAN	FlexCAN
CRC	CRC	CRC
	Hse_lp	HSE-H
CRIPIO	Mu_lp	MU
DIO	Siul2_Dio_Ip	SIUL2
EEP	Sd_Emmc_lp	uSDHC
ETH	GMAC	GMAC
FEE	NA	NA
FLS	Qspi_lp	QuadSPI
FR	FR	Flexray
	Etm In	FTM
		(FlexTimer)
GPT	Pit	PIT
	Rtc_lp	RTC
	Stm_ip	STM
12C	I2c_lp	12C
	Etm In	FTM
ICU		(FlexTimer)
	Siul2_lcu_lp	SIUL2
	Wkpu_lp	WKPU
LIN	LinFlex	LINFlexD
	Cache_Ip	Cache_M7
MCL	Dma_lp	DMA_CRC
	Dma_lp (Enhanced Direct Memory Access (PDMA - Peripheral eDMA))	eDMA3
	Clock_lp	MC_CGM
	Clock_Ip	FXOSC
	Clock_Ip	SIRC
	Clock_Ip	FIRC
MCU	Clock_Ip	CMU
IVICO	Clock_Ip	DFS
	Clock_Ip	PLLDIG
	Clock_lp	SRAMC
	Power_lp	MC_ME
	Power_lp	PMC

#### Software Content

	Power_lp	MC_RGM
	Ram_lp	STCU2
	NA	SIUL2
OCOTP	Ocotp_lp	OCOTP
001	Etm In	FTM
		(FlexTimer)
	System_lp	MCM
Platform	Intctrl_lp	NVIC
	Mpu_lp	MPU
PORT	Siul2_Port_Ip	SIUL2
PWM	Etm lp	FTM
		(FlexTimer)
QD	Ftm_lp	FIM (FlowTimor)
	Semal2 In	
RM		
CDI		
		SPI
	imu_ip	
UARI		LINFIEXD
WDG	swt_ip	SWI
RESOURCE	-	-
DEM	-	-
DET	-	-
ECUC	-	-
OS	-	-
ECUM	-	-
WDGIF	-	-
MEMIF	-	-
ETHIF	-	-
ETHTRCV	-	-
ETHSWT	-	-
LINIF	-	-
CANIF	-	-
CRYIF	-	-
CSM	-	-
RTE	-	-
FrIf	-	

# 3. Supported Targets

The software described in this document is intended to be used with microcontroller devices of

NXP Semiconductors, including:

- S32G2
- S32G3

## 4. Quality, Standards Compliance and Testing Approach

RTD product is developed according to NXP Software Development Processes that are Automotive-SPICE, ISO26262, IATF16949 and ISO9001 compliant.

RTD SW packages (starting with Beta releases) contain drivers as eclipse plugins for Elektrobit tresos or S32 Design Studio.

For each driver:

- Source code + configuration templates
- Driver User Manual
- Driver Integration Manual
- Driver Example Application

For the entire package:

• RTD Release Note

RTD SW packages (starting with Beta releases) are accompanied by software quality packages containing the following deliverables:

For each RTD driver:

- Driver Test Specification
- Driver Test Summary Report
- Driver MISRA Summary Report
- Driver HIS Summary Report

Real-Time Drivers Product Brief- S32G, Product Brief, Rev. 1, 02/2023

NXP Semiconductors

- Driver Code Coverage Summary Report
- Driver Traceability Matrix
- Driver VSMD Report
- Driver CWE Report
- Driver Compiler Warnings Report
- Driver Profile Report
- Driver Ram Size Report
- Driver Size Report
- Driver Static analysis Report (added only on customer request)

For the entire RTD package:

- RTD Test Summary Report
- RTD Quality Matrix

SW Testing approach is documented in RTD Test Strategy document that contains the following information and can be shared with customers in request.

- Testing scope and objectives
- Test levels: unit tests, unit integration tests
- Test types: functional, non-functional, regression tests, robustness, performance tests, conformance testing
  - Test techniques: white-box, black-box tests
  - o Test cases organization and prioritization
  - Test deliverables (test report, test specification, code coverage report, traceability matrix, static analysis report)

### **5. Document Information**

Table 1. S	Sample	revision	history
------------	--------	----------	---------

Revision number	Date	Substantive changes
1.0	01/2023	Initial release

#### How to Reach Us:

Home Page: nxp.com

Web Support: nxp.com/support Information in this document is provided solely to enable system and software implementers to use NXP products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document. NXP reserves the right to make changes without further notice to any products herein.

NXP makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does NXP assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in NXP data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. NXP does not convey any license under its patent rights nor the rights of others. NXP sells products pursuant to standard terms and conditions of sale, which can be found at the following address: <u>nxp.com/SalesTermsandConditions</u>.

NXP, the NXP logo, NXP SECURE CONNECTIONS FOR A SMARTER WORLD, COOLFLUX, EMBRACE, GREENCHIP, HITAG, I2C BUS, ICODE, JCOP, LIFE VIBES, MIFARE, MIFARE CLASSIC, MIFARE DESFire, MIFARE PLUS, MIFARE FLEX, MANTIS, MIFARE ULTRALIGHT, MIFARE4MOBILE, MIGLO, NTAG, ROADLINK, SMARTLX, SMARTMX, STARPLUG, TOPFET, TRENCHMOS, UCODE, Freescale, the Freescale logo, AltiVec, C 5, CodeTEST, CodeWarrior, ColdFire, ColdFire+, C Ware, the Energy Efficient Solutions logo, Kinetis, Layerscape, MagniV, mobileGT, PEG, PowerQUICC, Processor Expert, QorIQ, QorIQ Qonverge, Ready Play, SafeAssure, the SafeAssure logo, StarCore, Symphony, VortiQa, Vybrid, Airfast, BeeKit, BeeStack, CoreNet, Flexis, MXC, Platform in a Package, QUICC Engine, SMARTMOS, Tower, TurboLink, and UMEMS are trademarks of NXP B.V. All other product or service names are the property of their respective owners. ARM, AMBA, ARM Powered, Artisan, Cortex, Jazelle, Keil, SecurCore, Thumb, TrustZone, and µVision are registered trademarks of ARM Limited (or its subsidiaries) in the EU and/or elsewhere. ARM7, ARM9, ARM11, big.LITTLE, CoreLink, CoreSight, DesignStart, Mali, mbed, NEON, POP, Sensinode, Socrates, ULINK and Versatile are trademarks of ARM Limited (or its subsidiaries) in the EU and/or elsewhere. All rights reserved. Oracle and Java are registered trademarks of Oracle and/or its affiliates. The Power Architecture and Power.org word marks and the Power and Power.org logos and related marks are trademarks and service marks licensed by Power.org.

© 2023 NXP B.V.

Document Number: 1 Rev. 1 02/2023